



PATENT
Attorney Docket No. 207617

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4/2/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Dirksen et al.

Application No. 09/737,905

Art Unit: 1765

Examiner: V. Perez-Ramos

Filed: December 15, 2000

For: METHOD OF POLISHING OR
PLANARIZING A SUBSTRATE

COPY OF PAPERS
ORIGINALLY FILED

RESPONSE TO OFFICE ACTION

Commissioner for Patents
Washington, D.C. 20231

RECEIVED

MAR 19 2002

TC 1700

Dear Sir:

In response to the Office Action dated December 31, 2001, please consider the following remarks.

REMARKS

The Pending Claims

Claims 1-16 are currently pending. Claims 1-16 are directed to a method of polishing a substrate with a composition comprising a metal oxide abrasive and a liquid carrier, wherein the composition has a pH of about 7 or less and the metal oxide abrasive has a total surface hydroxyl group density no greater than about 3 hydroxyl groups per nm². Reconsideration of the pending claims is respectfully requested.

Summary of the Office Action

Claims 1-16 stand rejected under 35 U.S.C. § 103(a) as obvious over Adams et al. (i.e., U.S. Patent 5,664,990) and Kaneko et al. (i.e., U.S. Patent 5,114,881).

Discussion of the Obviousness Rejection

The Office Action asserts that Adams et al. discloses polishing compositions for metal-containing substrates comprising a metal oxide abrasive and a liquid carrier at a pH of less than 5. The Office Action further asserts that Kaneko et al. discloses silica powder having a hydroxyl density of 0.1 to 4 groups/100 Å². While the Office Action acknowledges that Adams et al. fails to disclose the use of a metal oxide abrasive having a total surface